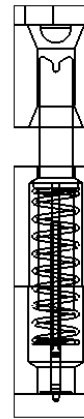
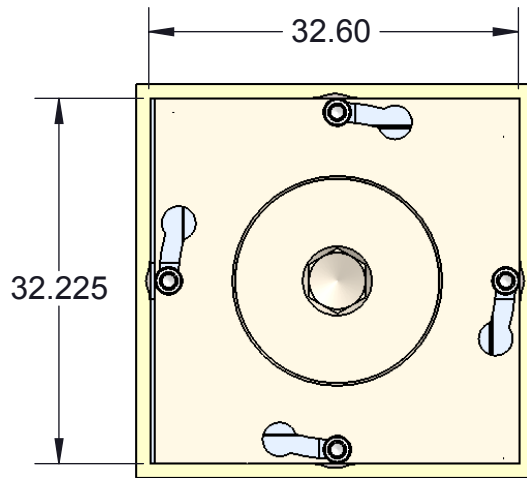


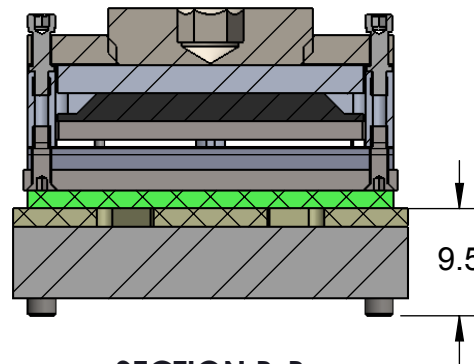
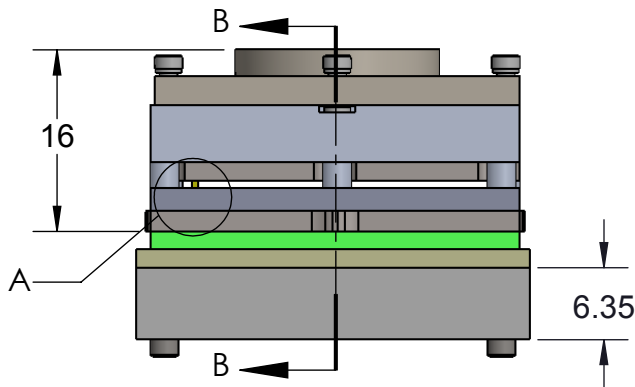
SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

Features

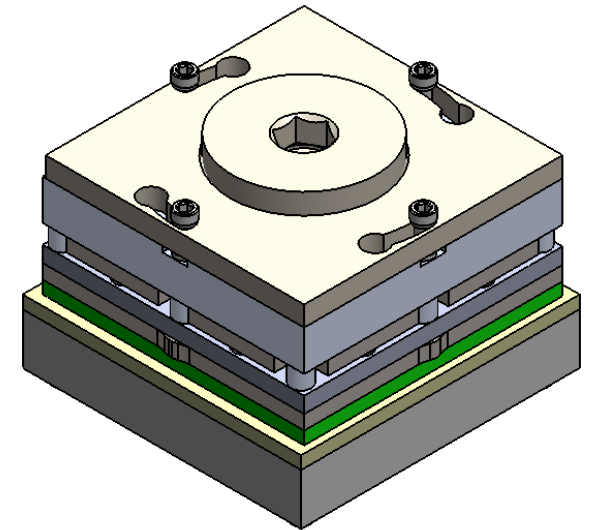
- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time



DETAIL A
SCALE 8 : 1




SECTION B-B



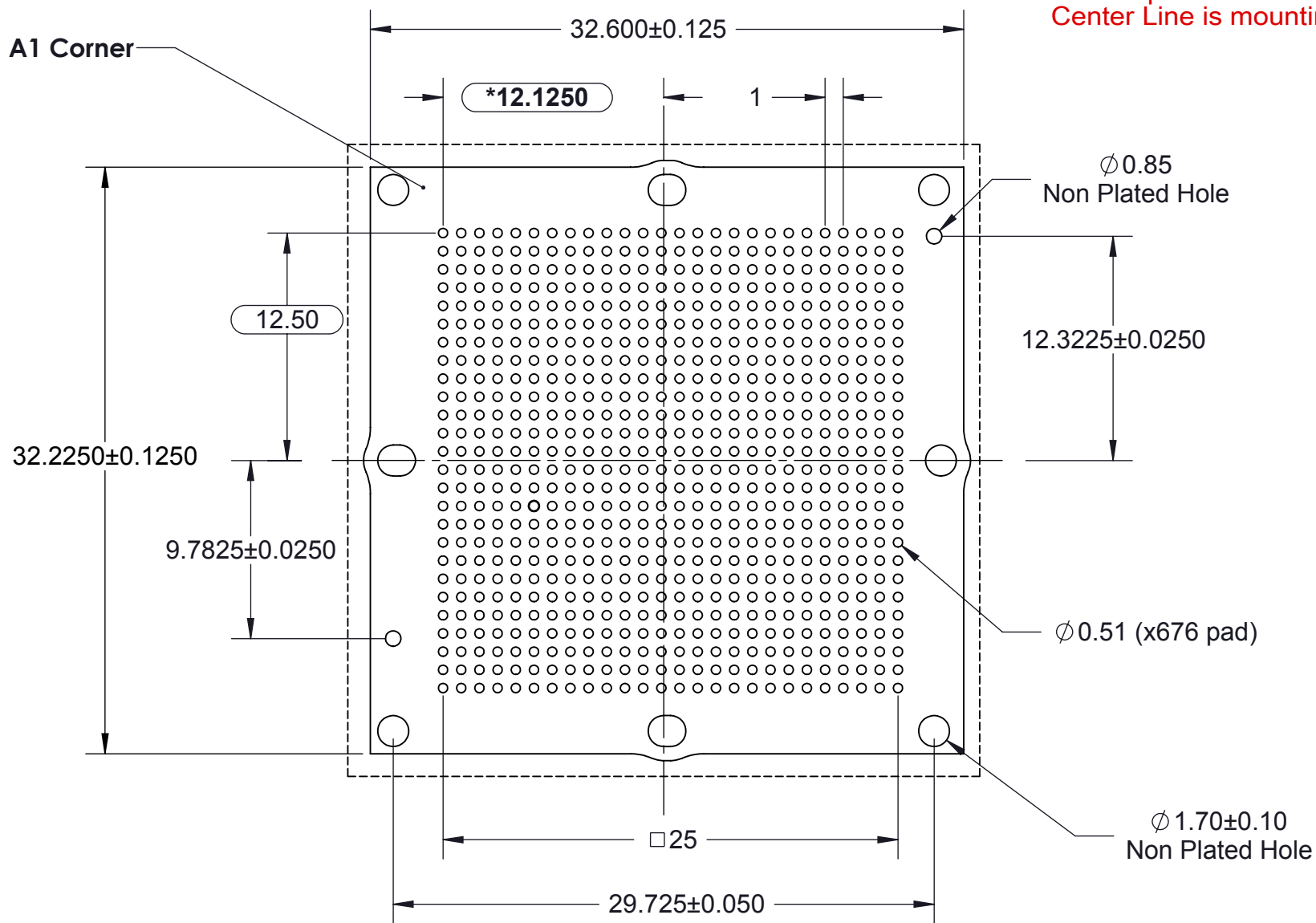
Description: SBT-BGA Socket 27x27mm, 1mm, 26x26 array

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6002 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: Weight: 51.80	STATUS: Released	SHEET: 1 OF 4	REV. F
		ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 3:2
		FILE: SBT-BGA-6002	DATE: 03/29/10	


*Note: BGA pattern is not symmetrical with respect to the mounting holes.
Center Line is mounting holes center

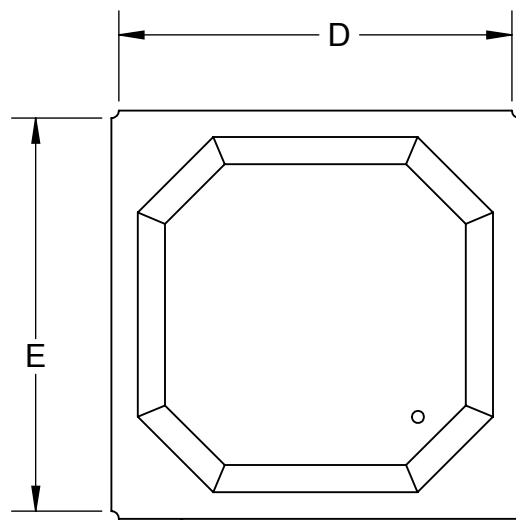


Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

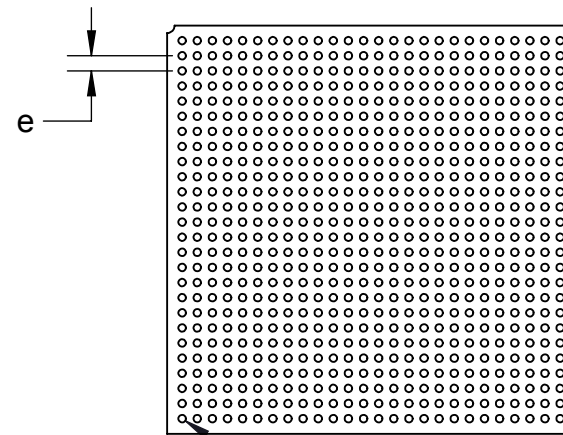
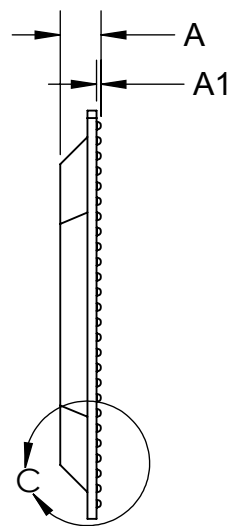
Description: Recommended Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6002 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: Weight: 51.80	STATUS: Released	SHEET: 2 OF 4	REV. F
		ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 3:1
		FILE: SBT-BGA-6002	DATE: 03/29/10	

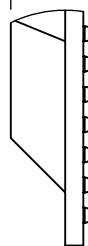


0.20



ϕ	0.25	Z	X	Y
ϕ	0.10			

0.20 Z



0.20

DETAIL C
SCALE 4 : 1

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	Minimum	Maximum
A		2.5
A1	0.40	0.60
b	0.50	0.70
D	27.0 BSC	
E	27.0 BSC	
e	1.00 BSC	

26x26 array

Description: BGA Spec

Primary dimension units are millimeters. Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-6002 Drawing



Ironwood Electronics, Inc.
Tele: (800) 404-0204
www.ironwoodelectronics.com

Material: Material <not specified>
Finish:
Weight: 51.80

STATUS: Released

ENG: V. Panavala

FILE: SBT-BGA-6002

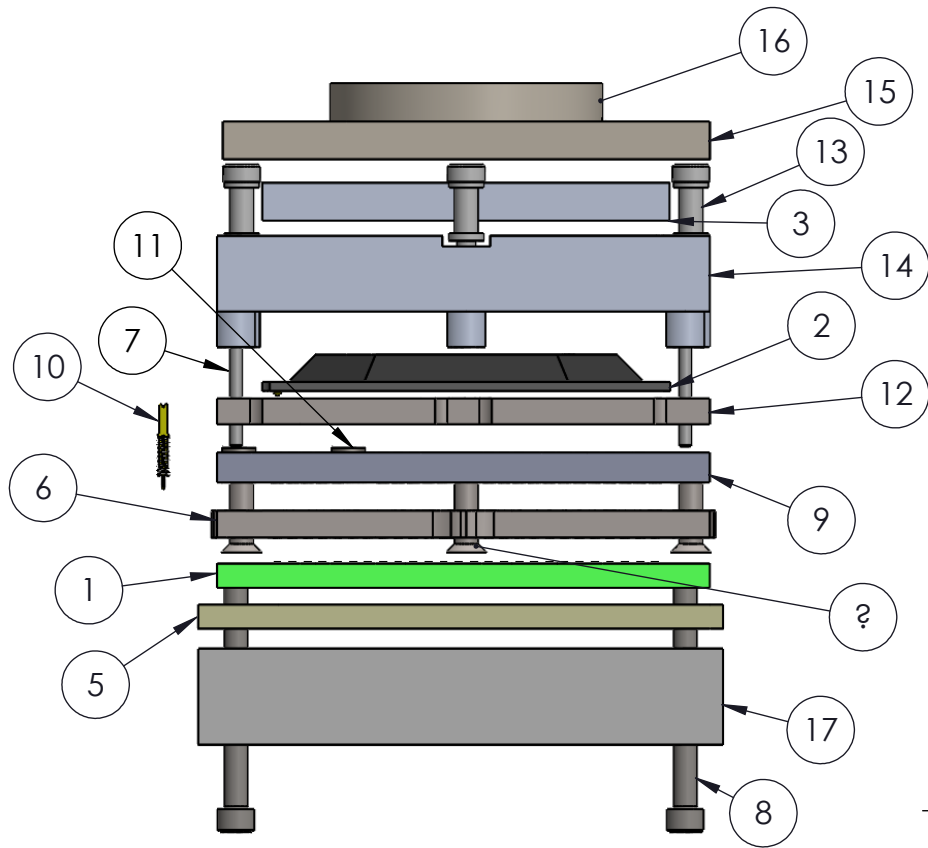
SHEET: 3 OF 4

DRAWN BY: M. Raske

DATE: 03/29/10

REV. F

SCALE: 2:1



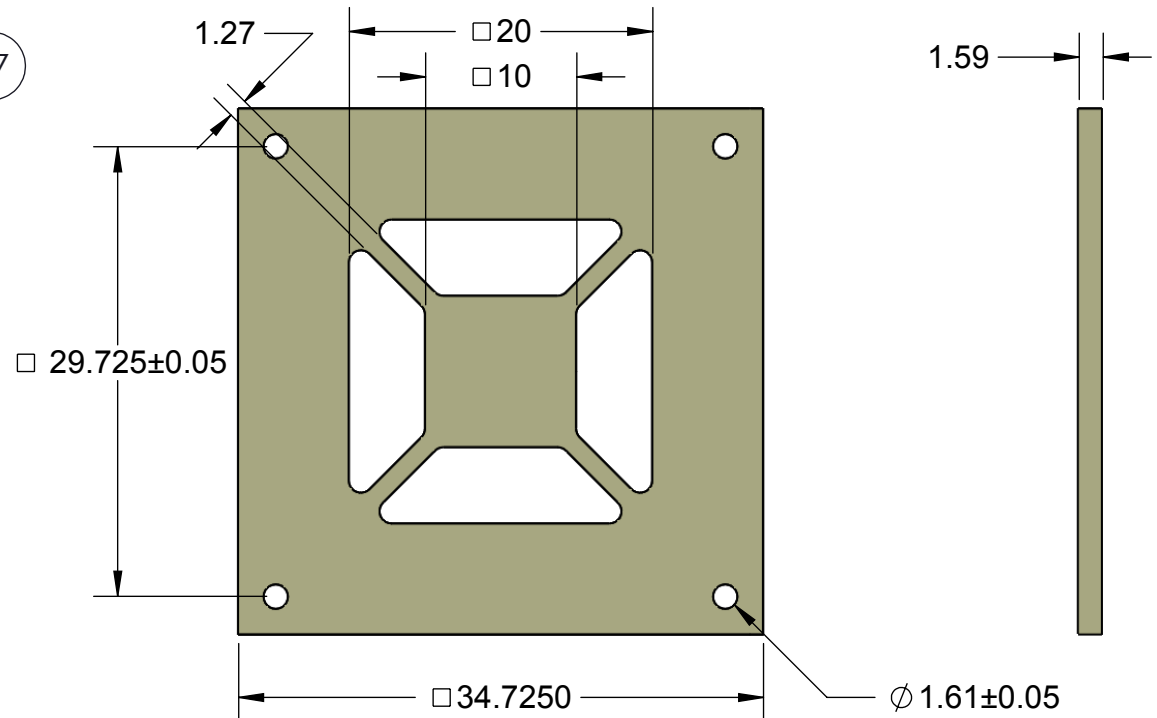
ITEM NO.	Description	Material
1	Test PCB BGA676C	FR4
2	676 pin BGA package, 1mm Pitch	Material <not specified>
3	Compression Plate, 26.95 X 26.95	7075-T6 Aluminum Alloy
4	#0-80, 90 deg., head pin guide screw, Peek material 5.5715mm overall Length	PEEK unfilled
5	Insulation Plate 27mm IC	FR4
6	Bottom Guide 26x26 array 1mm pitch	PEEK Ceramic filled
7	Dowel Pin, 1/32" x 3/8", SS	Chrome Stainless Steel
8	#0-80 X .625 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel
9	Middle Guide 26x26 array 1mm pitch	PEEK Ceramic filled
10	Pogo Pin, 1mm Pitch SBT BGA pin	N/A
11	Floating Guide Spring	Alloy Steel (SS)
12	Floating Guide 26x26 array 1mm pitch	PEEK Ceramic filled
13	#0-80 Shoulder Screw, 0.062" thread length	Stainless Steel (303)
14	Socket Base SBT 27x27mm Ni plated 0.375mm shift 1mm and 1.27 mm pitch IC	7075-T6 Aluminum Alloy
15	Socket Lid, 32.225 X 32.225	7075-T6 Aluminum Alloy
16	Compression Screw, M18	7075-T6 Aluminum Alloy
17	SBT Ni plt backing plt 27mm IC	7075-T6 Aluminum Alloy


Rev	Date	Initials	Description
A	11/13/09	VP	Original
B,C	3/29/10	VP	Added posts to the socket base
D	7/23/13	RP	SW drawing template update
E	10/23/13	GL	Removed 1/32" x 5/16" Dowel Pin replaced with 1/32" x 3/8" Dowel Pin
F	03/12/15	DH	Updated layout page,

Description: Socket Spec

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.



 SBT-BGA-6002 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: Weight: 51.80	STATUS: Released ENG: V. Panavala FILE: SBT-BGA-6002	SHEET: 4 OF 4 DRAWN BY: M. Raske DATE: 03/29/10	REV. F SCALE: 2:1
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